Filename: PMP8252_REVB_bom.xls

Date: 07/06/2012

PMP8252_REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
	C1	0.047uF	Capacitor, Ceramic, 100V, X7R, 15%	1206	STD	STD
1	C10	330pF	Capacitor, Ceramic, 3kV, NP0, C0G, 10%	1808	Std	Std
1	C100	10pF	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C101	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C11	22uF	Capacitor, Aluminum, 16V, 20%	0.201 x 0.262 inch	EEVFK1C220R	Panasonic
3	C12, C13, C17	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C15	100pF	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
6	C18, C19, C20, C21, C22, C24	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	STD	STD
3	C2, C3, C27	47uF	Capacitor, Ceramic, 6.3V, X5R, 15%	1210	STD	STD
1	C23	47uF	CAP ELECT 47UF 80V FK SMD	0.457 x 0.406	EEE-FK1K470P	Panasonic
2	C4, C7	1000uF	Capacitor, Aluminum, 6.3V, 20%	0.315 inch	6.3V ZL 1000uF 10 X 12.5mm	Rubycon
2	C5, C16	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C6	0.022uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
3	C8, C14, C25	1uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	STD	STD
1	C9	4.7uF	Capacitor, Ceramic, 16V, X7R, 15%	0805	STD	STD
1	D100	MBRA140LT3	Diode, Schottky, 1-A, 40-V	SMA	MBRA140LT3	Motorola
1	D2	5.1V	Diode, Zener, 5.1-V	SOT23	BZX84C5V1LT1	ON Semi
7	D3, D4, D5, D6, D7, D8, D9	MMSD914T1	Diode, Switching, 100-V, 200-mA, 225-mW,	SOD-123	MMSD914T1	On Semi
4	J1, J2, J3, J4	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	L2	2.4uH	Inductor, Planar, 36A,	0.770 x 0.780 inch	PA1494.242	Pulse
1	L3	1mH	INDUCT PWR 1MH SMD	0.244 x 0.244 inch	PG0087.105NLT	Pulse
1	L4	10uH	Inductor, SMTPower, 6A	0.492 x 0.492 inch	PF0553-103NL	Pulse
2	Q1, Q2	BSC190N12NS3	MOSFET N-CH 120V 44A TDSON-8	TDSON-8	BSC190N12NS3	Infineon
1	Q10	MMBT2222A	TRANSISTOR, NPN, HIGH-PERFORMANCE, 500mA	SOT-23	MMBT2222A	Fairchild
2	Q11, Q100	MMBT2907A	Transistor, PNP, -60V, -600mA, 225-W	SOT23	MMBT2907ALT1	On Semi
1	Q3	IRF6216PBF	MOSFET, PChan, -150V, -2.2A, 0.24 Ohm	SO8	IRF6216PBF	IR
4	Q4, Q5, Q6, Q7	CSD17312Q5-R	MOSFET N-CH 30V 100A 8SON	QFN5X6mm	CSD17312Q5-R	TI
1	Q8	DNLS350Y	TRANS NPN BIPO 50V 3A SOT89-3	SOT-89	DNLS350Y	Diodes Inc.
1	R1	1k	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R100	30.1k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R101	680	Resistor, 680 Ohms, 1W, 5%	2512	STD	STD
1	R11	24.9k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	R12, R19	60.4k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R13	301	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R14	6.04k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	R16, R24	0	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R17	4.70k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R18	1.21k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R2	4.7	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R20	1	Resistor, Metal Film, 1/4 watt, 5%	1206	Std	Std
1	R21	2.7	Resistor, Chip, 1/16W, 5%	0805	Std	Std

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COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	R3	499	Resistor, Chip, 1/16W, 5%	0805	Std	Std
3	R4, R5, R15	10k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
4	R6, R8, R22, R23	1k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R7	100k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
2	R9, R10	90.9k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	T1	PH0810.008NL	Transformer, Planar	0.850 x 0.920 inch	PH0810.008NL	Pulse
1	T2	PA1005.100NL	Transformer, Current Sense	0.284 x 0.330 inch	PA1005.100NL	Pulse
3	TP1, TP2, TP4	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP3, TP5	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	UCC2897APW	IC, Current-Mode Active Clamp PWM Controller	PW20	UCC2897APW	TI
1	U2	TLV431	IC, Low-Voltage Adjustable Shunt Regulator	SOT23-3	TLV431AIDBZ	TI
1	U4	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay

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